Call for VIS/VR/CG Surveys

TVCG welcomes and encourages the submission of survey papers in all areas in its scope, computer graphics, visualization, and augmented and virtual reality. These survey papers, called VIS/VR/CG Surveys, are meant to be easily accessible to non-experts and are designed to provide a thorough, integrative, up-to-date, and comprehensive narration of the existing body of research in the survey's target domain. They cover the subject's theory as well as its practice, point out existing trends, enable a critical comparison of existing research efforts and results, and in some occasions, also shed light on developments in the commercial arena. Survey papers are up to 20 double-columned pages in length and are rigorously peer-reviewed by domain experts.

VIS/VR/CG Surveys have the specific aim to (1) provide unfamiliar readers a quick gateway into a VIS/VR/CG-related research domain, and (2) help professionals working in the field stay abreast with developments in this rapidly evolving area of research. Topics of interest are: information and scientific visualization, visual analytics, virtual and augmented reality, computer graphics, and others.

VIS/VR/CG Surveys can be orally presented at the IEEE VIS, ISMAR, IEEE VR, or other collaborating conferences. Authors aiming for VIS 2021, IEEE VR 2022, or ISMAR 2021, should plan to submit a VIS/VR/CG Survey paper to TVCG by the following deadlines.

IEEE VIS 2021: November 30th, 2020 ISMAR 2021: December 31st, 2020 IEEE VR 2022: April 30th, 2021

Authors aiming for a graphics conference, please refer to the partner conferences listed here and submit the survey paper 10-12 months before the intended graphics conference begins.

Submissions are accepted all year long but sending them by this date will give enough time for the revision process to be concluded before the conference program has been finalized.

In order to test an idea, if in doubt, please send an email message with a quick overview to:

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